



Wide-Bandgap Materials and Applications

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submissions:

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Message from the Guest Editors

Wide-bandgap semiconductors are rapidly emerging as disruptive materials for a wide range of applications. Even though some products are already available in the market, efforts are still needed to improve the performance and reliability of the devices as well as to identify novel materials and structures toward widening the possible application fields.

In order to showcase the most recent advancements, we are requesting submissions for a Special Issue on wide-bandgap materials and their applications. Topics of interest for this Special Issue include, but are not limited to:

- Wide-bandgap elemental and compound semiconductors: gallium nitride, silicon carbide, gallium oxide, aluminum nitride, boron nitride, diamond, to name but a few examples;
- Materials and devices for power electronics, RF applications, and optoelectronics, including extreme environments such as space applications;
- The full range of the fabrication process, from substrate, growth, and processing to electrical, optical, and defect characterization, as well as reliability and packaging;
- Device integration and novel device structures;
- Tutorials, reviews, and perspectives.





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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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